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## IN THE CLAIMS

(Currently Amended) A semiconductor laser light emitting device comprising: 1. a stacked film composed of a stack of group III nitride semiconductor films;

wherein each containing at least one kind group III nitride semiconductor film comprises an element selected from the group consisting of aluminum, gallium, indium, and boron;

wherein, an upper portion of said stacked film stack of group III nitride semiconductor films comprises is formed into a ridge like stripe, to form a current injection region;

wherein a current injection width Wst of said current injection region is at a value in a range of 1  $\mu$ m  $\leq$  Wst  $\leq$  3  $\mu$ m[[,]]; and

wherein said current injection region is formed on an active layer;

a current non-injection region formed on both sides of said ridge like strip current injection region, wherein [[;]] at least part of said current non-injection region comprises is made from a material expressed by a chemical formula  $Al_xGa_{1-x}N$  ( $0 \le x \le 1.0$ ); wherein the component ratio "x" of Al is at a value in a range of  $0.3 \le x \le 1.0$ , so that said semiconductor laser light emitting device is configured as an index guide type semiconductor laser light emitting device; and

expressed by a chemical formula  $Al_xGa_{1-x}N$  (0.3  $\leq x \leq 1.0$ ), and has have a combined thickness of less than or equal to 0.2  $\mu$ m but greater than zero. wherein the group III nitride semiconductor films a film located between an the active

## Claims 2-4 (Cancelled)

5. (Original) A semiconductor laser light emitting device according to claim 1, wherein a difference  $\Delta n$  between an effective refractive index n1 of said current injection region in the film stacking direction and an effective refractive index n2 of said current non-injection region in the film stacking direction is in a range of  $0.007 \le \Delta n = (n1-n2) \le 0.012$ .

## Claims 6-8 (Cancelled)

9. (Currently Amended) A semiconductor laser light emitting device comprising:

a stacked film composed of a stack of group III nitride semiconductor films;

wherein each containing at least one kind group III nitride semiconductor film comprises

an element selected from the group consisting of aluminum, gallium, indium, and boron;

wherein, an upper portion of said stacked film stack of group III nitride semiconductor films comprises is formed into a ridge like stripe, to form a current injection region;

wherein a current injection width Wst of said current injection region is at a value in a range of 1  $\mu$ m  $\leq$  Wst  $\leq$  3  $\mu$ m[[,]]; and

wherein said current injection region is formed on an active layer;

a current non-injection region formed on both sides of said ridge like strip current

injection region, wherein [[;]] and at least part of said current non-injection region comprises is

made from a material expressed by a chemical formula  $Al_xGa_{1-x}N$  ( $0 \le x \le 1.0$ );, wherein the component ratio "x" of Al is at a value in a range of 0.15 < x < 0.30[[,]] so that said semiconductor laser light emitting device is configured as a weak index type pulsation semiconductor laser light emitting device; and

wherein the group III nitride semiconductor films a film located between an the active layer and the current non-injection region of the stacked film made from, comprises a material expressed by a chemical formula  $Al_xGa_{1-x}N$  (0.15  $\leq x \leq 0.30$ ), and has have a combined thickness of less than or equal to 0.2  $\mu$ m but greater than zero.

Claims 10-12 (Cancelled)

13. (Original) A semiconductor laser light emitting device according to claim 9, wherein a difference  $\Delta n$  between an effective refractive index n1 of said current injection region in the film stacking direction and an effective refractive index n2 of said current non-injection region in the film stacking direction is in a range of  $0 < \Delta n = (n1-n2) < 0.007$ .

Claims 14-24 (Cancelled)

25. (Currently Amended) A semiconductor laser light emitting device comprising:
a stack of group III nitride semiconductor films each comprising at least one element
selected from the group of aluminum, gallium, indium, and boron;

an upper portion of said stacked film stack of group III nitride semiconductor films comprises forming a ridge like stripe for a current injection region;

wherein a current non-injection region formed on both sides of said ridge-like strip, wherein at least part of said current non-injection region comprises is made from a material expressed by a chemical formula  $Al_xGa_{1-x}N$  ( $0 \le x \le 1.0$ ), and wherein the component ratio "x" of Al is between 0.3 and 1.0; and

a p-side electrode is formed on and in contact with the current non-injection region.

26. (Currently Amended) A semiconductor laser light emitting device comprising:

a stack of group III nitride semiconductor films each comprising at least one element
selected from the group of aluminum, gallium, indium, and boron;

an upper portion of said stacked film forming a ridge-like stripe for a current injection region;

a current non-injection region formed on both sides of said ridge-like strip, wherein at least part of said current non-injection region is made from a material expressed by a chemical formula  $Al_xGa_{1-x}N$  ( $0 \le x \le 1.0$ ), and wherein the component ratio "x" of Al is between 0.3 and 1.0; and

a contact layer formed in between on the current injection region, wherein the current non-injection region is formed on both sides of said contact layer.

27. (Previously Presented) A semiconductor laser light emitting device according to claim 26, wherein the contact layer is formed on the ridge-like stripe.

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- 28. (Previously Presented) A semiconductor laser light emitting device according to claim 27, wherein the contact layer is in contact with the ridge-like stripe.
- 29. (Previously Presented) A semiconductor laser light emitting device according to claim 26, further comprising a p-side electrode is formed on and in contact with the contact layer.

30. (Currently Amended) A semiconductor laser light emitting device comprising:
a stack of group III nitride semiconductor films;

wherein each group III nitride semiconductor film comprises an element selected from the group consisting comprising at least one element selected from the group of aluminum, gallium, indium, and boron;

wherein, an upper portion of said stacked film stack of group III nitride semiconductor films comprises forming a ridge like stripe for a current injection region;

wherein a current non-injection region formed on both sides of said ridge like strip current injection region, wherein at least part of said current non-injection region comprises is made from a material expressed by a chemical formula  $Al_xGa_{1-x}N$   $(0 \le x \le 1.0)$ ; and

wherein the group III nitride semiconductor films a film located between an the active layer and the current non-injection region of the stacked film made from, comprises a material expressed by a chemical formula  $Al_xGa_{1-x}N$  (0.15  $\leq x \leq 0.30$ ), and having have a combined thickness of less than or equal to 0.2  $\mu$ m but greater than zero.